

WHAT IS CLAIMED IS:

1. A cleaning mechanism for an image sensor package, the cleaning mechanism being cleaning the substrate and the frame layer arranged on the substrate of the image sensor to form a chamber between the frame layer and the substrate, the mechanism comprising:
 - a seal up body being formed with a cleaning room, the substrate formed with frame layer being fixed on the top end of the cleaning room, then, the chamber of the substrate being faced down direction from the cleaning room;
 - a cleaning device being mounted on the bottom end of the cleaning room of the seal up body for cleaning the chamber of the substrate by cleaner.
2. The cleaning mechanism according to claim 1, wherein seal up body includes a lower element, a periphery wall, and a upper cover.
3. The cleaning mechanism according to claim 1, wherein further includes a vacuum pump is arranged within the cleaning room.
- 15 4. The cleaning mechanism according to claim 1, wherein the cleaner of the cleaning device is N2 or CO2.
5. The cleaning mechanism according to claim 1, wherein the cleaner of the cleaning device is water.